

Data requirements for semiconductor die —

Part 3: Mechanical, material and connectivity requirements

ICS 31.080.01

National foreword

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the ES title page, pages 2 to 8 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

This Published Document, having been prepared under the direction of the Electrotechnical Sector Committee, was published under the authority of the Standards Committee and comes into effect on 15 December 1999

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Amendments issued since publication

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